SMT Inductors

Transponder coils
Size 4.5 × 3.2 × 3.2 mm, 4532 (IEC) / 1812 (EIA)

Series/Type: B82451A2384D000
Date: September 2019
Transponder coils

Size 4532 (IEC) / 1812 (EIA)
Rated inductance 2.38 mH
Sensitivity 7.6 mV/μT

Construction
- Ferrite drum core
- Winding: laser-welded with non-solderable wire
- Flame-retardant molding

Features
- Temperature range up to +125 °C
- Qualified to AEC-Q200
- High sensitivity in Z direction
- High quality factor
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- RoHS-compatible

Applications
- Transponder coil in TPMS (Tire Pressure Monitoring Systems)

Terminals
- Base material CuSn6
- Layer composition Cu, Ag, Sn (lead-free)
- Electro-plated

Marking
- Marking on component:
  Manufacturer, L value (nH, coded without exponent), letter “D”, date of manufacture (YWWD)
- Minimum data on reel:
  Manufacturer, ordering code, L value, quantity, date of packing

Delivery mode and packing unit
- 12-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 2500 pcs./reel
Dimensional drawing and layout recommendation

1) Soldering area

Taping and packing

Blister tape

Reel
Technical data and measuring conditions

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Rated inductance ( L_R )</td>
<td>Measured with impedance analyzer Agilent 4294A or equivalent at frequency ( f_L ), 0.5 V, +20 °C</td>
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<tr>
<td>( Q ) factor ( Q_{\text{min}} )</td>
<td>Measured with impedance analyzer Agilent 4294A or equivalent at frequency ( f_Q ), +20 °C</td>
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<tr>
<td>Rated temperature ( T_R )</td>
<td>+125 °C</td>
</tr>
<tr>
<td>Self-resonance frequency ( f_{\text{res},\text{min}} )</td>
<td>Measured with impedance analyzer Agilent 4294A or equivalent, +20 °C</td>
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<tr>
<td>DC resistance ( R_{\text{max}} )</td>
<td>Measured at +20 °C</td>
</tr>
<tr>
<td>Solderability (lead-free)</td>
<td>Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (5 ±0.3) s</td>
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<tr>
<td></td>
<td>Wetting of soldering area ≥ 90%</td>
</tr>
<tr>
<td></td>
<td>(based on IEC 60068-2-58)</td>
</tr>
<tr>
<td>Resistance to soldering heat</td>
<td>+250 °C, 30 s (as referenced in JEDEC J-STD 020D)</td>
</tr>
<tr>
<td>Climatic category</td>
<td>40/125/56 (to IEC 60068-1)</td>
</tr>
<tr>
<td>Storage conditions</td>
<td>Mounted: −40 °C ... +125 °C</td>
</tr>
<tr>
<td></td>
<td>Packaged: −25 °C ... +40 °C, ≤ 75% RH</td>
</tr>
<tr>
<td>Weight</td>
<td>Approx. 120 mg</td>
</tr>
</tbody>
</table>

Characteristics and ordering codes

| \( L_R \) | \( L \) tolerance | \( f_L \), \( f_Q \) \( f_{\text{res},\text{min}} \) | \( Q_{\text{min}} \) | \( S_{\text{typ}} \) \( \frac{\text{mV}}{\mu\text{T}} \) | \( R_{\text{max}} \) | \( f_{\text{res}} \) MHz | Ordering code |
|-----------|------------------|-----------------------------|------------------|-----------------------------|------------------|-----------------|----------------|----------------|
| \( \mu \) H | ±5%              | 125                         | 25               | 7.6                         | 43               | > 1.5           | B82451A2384D000  |
Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.

- Particular attention should be paid to the derating curves given there.
- The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.

If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

The following points must be observed if the components are potted in customer applications:

- Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
- It is necessary to check whether the potting material used attacks or destroys the wire, wire insulation, plastics or glue.
- The effect of the potting material can change the high-frequency behaviour of the components.
- Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obligated to determine whether and to what extent their coating materials influence the component.
- Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.

Ceramics / Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.

Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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Release 2018-10